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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, Voltage Detect, WDT
Number of I/O	41
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	52-LQFP
Supplier Device Package	52-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21255sdfp-v2

1.2 Performance Overview

Table 1.1 outlines the Functions and Specifications for R8C/24 Group and Table 1.2 outlines the Functions and Specifications for R8C/25 Group.

Table 1.1 Functions and Specifications for R8C/24 Group

Item		Specification
CPU	Number of fundamental instructions	89 instructions
	Minimum instruction execution time	50 ns (f(XIN) = 20 MHz, VCC = 3.0 to 5.5 V) 100 ns (f(XIN) = 10 MHz, VCC = 2.7 to 5.5 V) 200 ns (f(XIN) = 5 MHz, VCC = 2.2 to 5.5 V)
	Operating mode	Single-chip
	Address space	1 Mbyte
	Memory capacity	Refer to Table 1.3 Product Information for R8C/24 Group
Peripheral Functions	Ports	I/O ports: 41 pins, Input port: 3 pins
	LED drive ports	I/O ports: 8 pins
	Timers	Timer RA: 8 bits × 1 channel Timer RB: 8 bits × 1 channel (Each timer equipped with 8-bit prescaler) Timer RD: 16 bits × 2 channels (Input capture and output compare circuits) Timer RE: With real-time clock and compare match function
	Serial interfaces	2 channels (UART0, UART1) Clock synchronous serial I/O, UART
	Clock synchronous serial interface	1 channel I ² C bus Interface ⁽¹⁾ Clock synchronous serial I/O with chip select
	LIN module	Hardware LIN: 1 channel (timer RA, UART0)
	A/D converter	10-bit A/D converter: 1 circuit, 12 channels
	Watchdog timer	15 bits × 1 channel (with prescaler) Reset start selectable
	Interrupts	Internal: 11 sources, External: 5 sources, Software: 4 sources, Priority levels: 7 levels
	Clock	Clock generation circuits
		3 circuits • XIN clock generation circuit (with on-chip feedback resistor) • On-chip oscillator (high speed, low speed) High-speed on-chip oscillator has a frequency adjustment function • XCIN clock generation circuit (32 kHz)
		Real-time clock (timer RE)
	Oscillation stop detection function	XIN clock oscillation stop detection function
	Voltage detection circuit	On-chip
	Power-on reset circuit	On-chip
Electrical Characteristics	Supply voltage	VCC = 3.0 to 5.5 V (f(XIN) = 20 MHz) VCC = 2.7 to 5.5 V (f(XIN) = 10 MHz) VCC = 2.2 to 5.5 V (f(XIN) = 5 MHz)
	Current consumption	Typ. 10 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 6 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 2.0 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 0.7 μA (VCC = 3.0 V, stop mode)
Flash Memory	Programming and erasure voltage	VCC = 2.7 to 5.5 V
	Programming and erasure endurance	100 times
Operating Ambient Temperature		-20 to 85°C (N version)
		-40 to 85°C (D version) ⁽²⁾
		-20 to 105°C (Y version) ⁽³⁾
Package		52-pin molded-plastic LQFP
		64-pin molded-plastic FLGA

NOTES:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Specify the D version if D version functions are to be used.
3. Please contact Renesas Technology sales offices for the Y version.

1.3 Block Diagram

Figure 1.1 shows a Block Diagram.

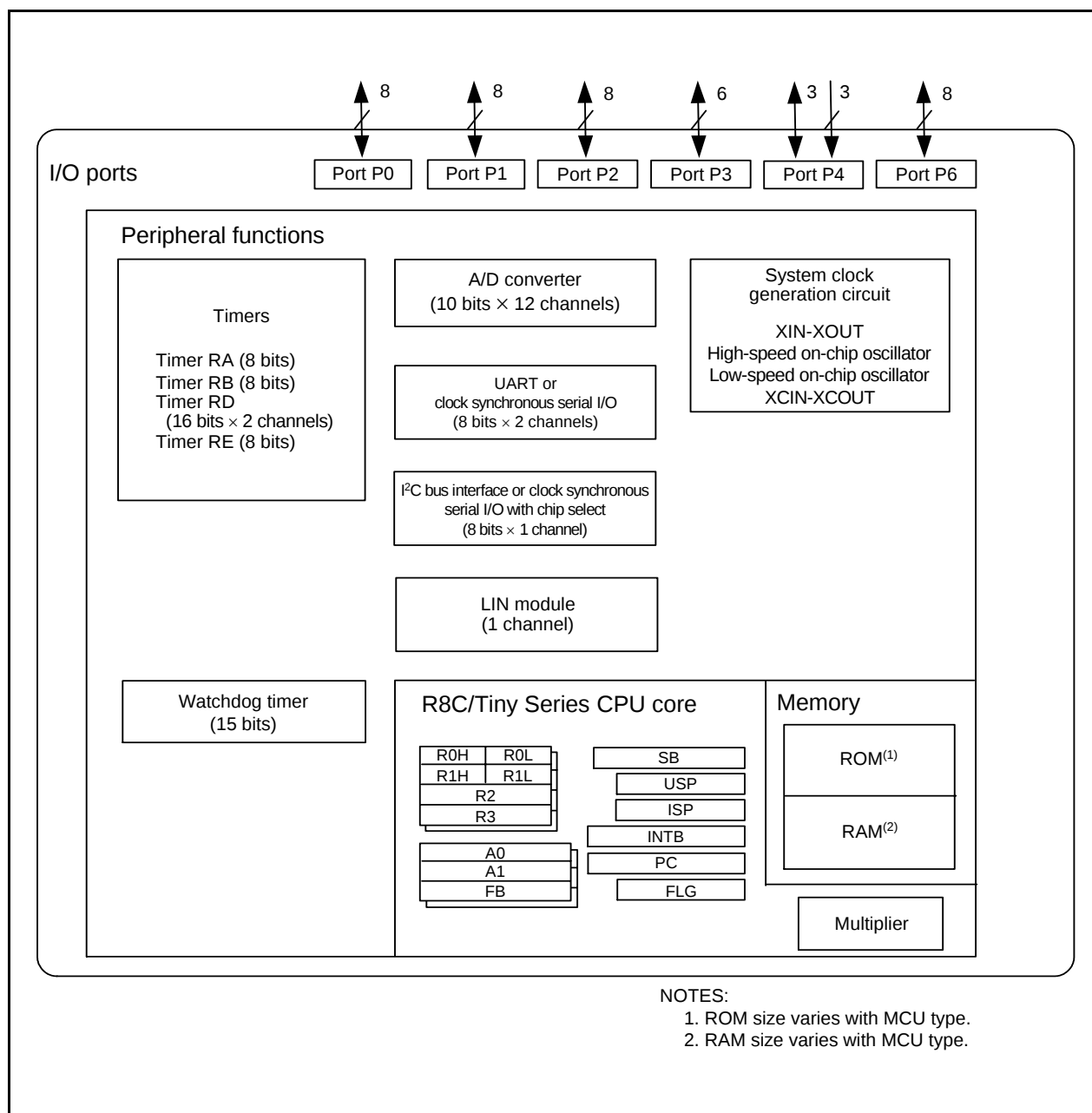


Figure 1.1 Block Diagram

1.5 Pin Assignments

Figure 1.4 shows PLQP0052JA-A Package Pin Assignments (Top View). Figure 1.5 shows PTLG0064JA-A Package Pin Assignments.

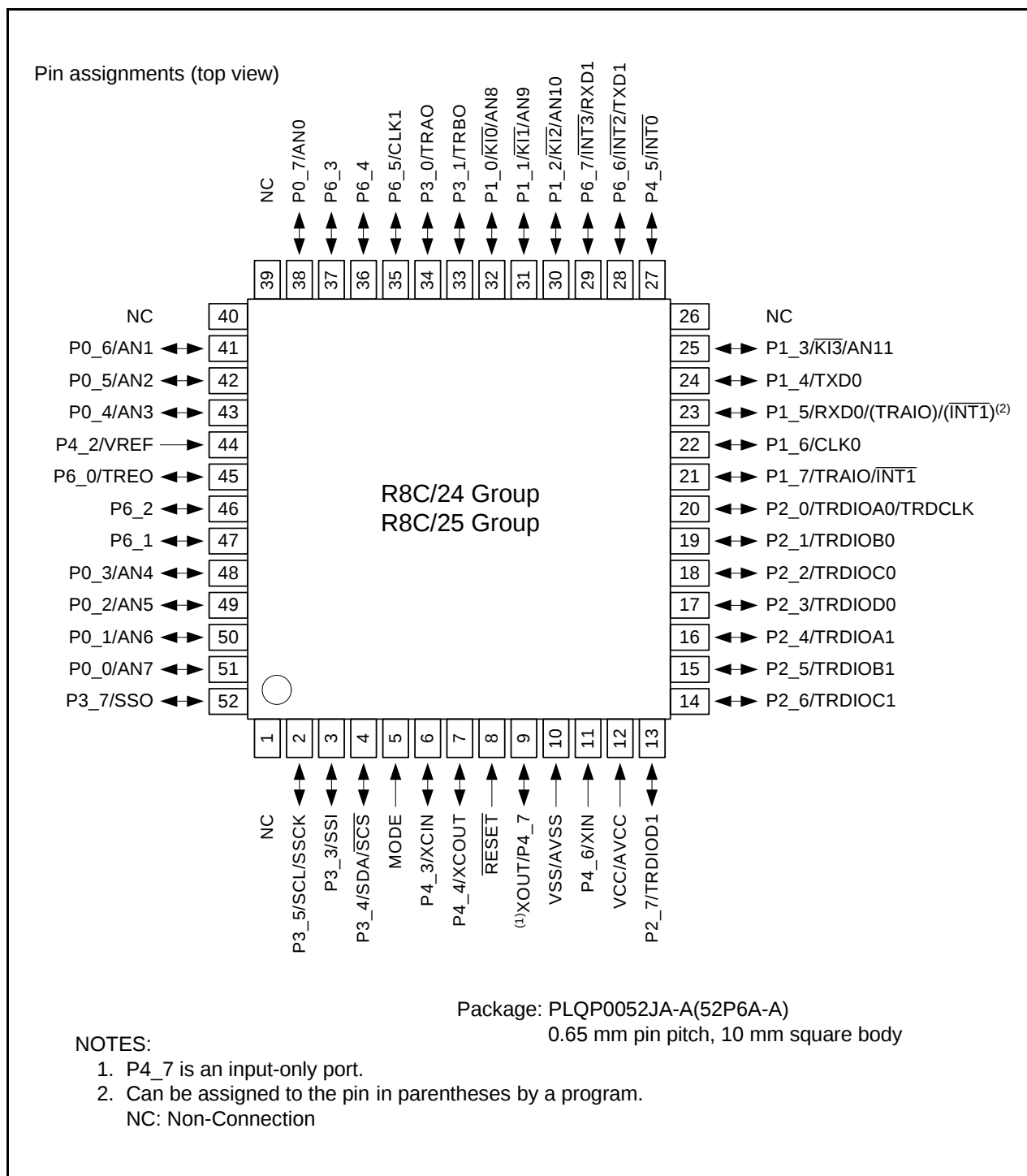


Figure 1.4 PLQP0052JA-A Package Pin Assignments (Top View)

1.6 Pin Functions

Table 1.5 lists Pin Functions.

Table 1.5 Pin Functions

Type	Symbol	I/O Type	Description
Power supply input	VCC, VSS	I	Apply 2.2 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	I	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Input "L" on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between the XCIN and XCOU pins. To use an external clock, input it to the XCIN pin and leave the XCOU pin open.
XCIN clock output	XCOU	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT3}}$	I	$\overline{\text{INT}}$ interrupt input pins. $\overline{\text{INT0}}$ is timer RD input pin. $\overline{\text{INT1}}$ is timer RA input pin.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O ports
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Serial interface	CLK0, CLK1	I/O	Transfer clock I/O pin
	RXD0, RXD1	I	Serial data input pins
	TXD0, TXD1	O	Serial data output pins
I ² C bus interface	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
Clock synchronous serial I/O with chip select	SSI	I/O	Data I/O pin
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin
Reference voltage input	VREF	I	Reference voltage input pin to A/D converter
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6_0 to P6_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. P2_0 to P2_7 also function as LED drive ports.
Input port	P4_2, P4_6, P4_7	I	Input-only ports

I: Input O: Output I/O: Input and output

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP, and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

3. Memory

3.1 R8C/24 Group

Figure 3.1 is a Memory Map of R8C/24 Group. The R8C/24 group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2-Kbyte internal RAM area is allocated addresses 00400h to 00BFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

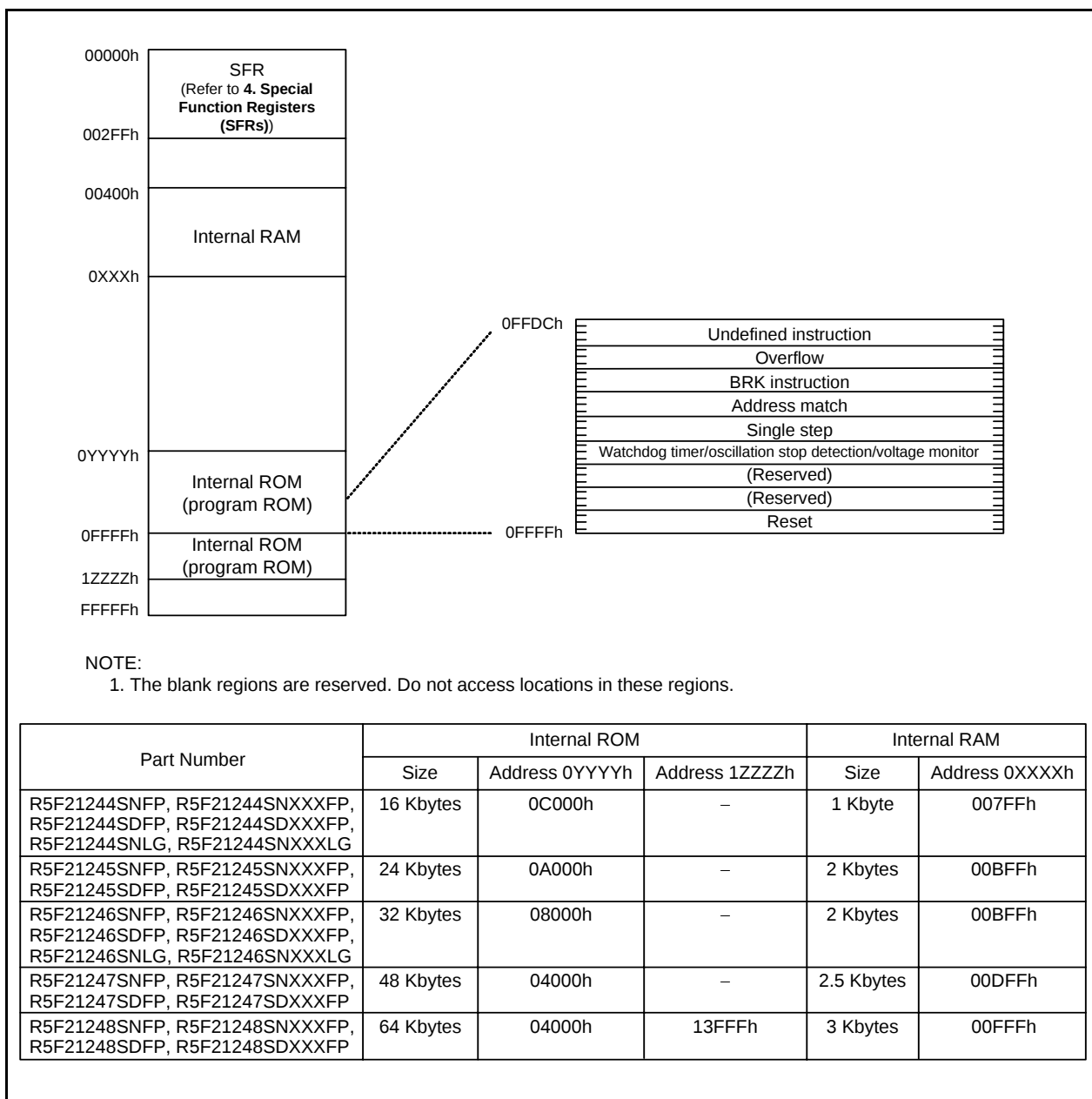


Figure 3.1 Memory Map of R8C/24 Group

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.7 list the special function registers.

Table 4.1 SFR Information (1)(1)

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h			
0009h			
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00X11111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			00h
0013h	Address Match Interrupt Enable Register	AIER	00h
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			00h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b ⁽⁶⁾
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h			
0027h			
0028h	Clock Prescaler Reset Flag	CPSRF	00h
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When shipping
002Ah			
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When shipping
002Ch	High-Speed On-Chip Oscillator Control Register 7	FRA7	When shipping
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	00h ⁽³⁾ 00100000b ⁽⁴⁾
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register ⁽⁵⁾	VW1C	00001000b
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h	Voltage Monitor 0 Circuit Control Register ⁽²⁾	VW0C	0000X000b ⁽³⁾ 0100X001b ⁽⁴⁾
0039h			
003Ah			
003Eh			
003Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Software reset, watchdog timer reset, and voltage monitor 1 reset or voltage monitor 2 reset do not affect this register.
3. The LVD0ON bit in the OFS register is set to 1 and hardware reset.
4. Power-on reset, voltage monitor 0 reset or the LVD0ON bit in the OFS register is set to 0, and hardware reset.
5. Software reset, watchdog timer reset, and voltage monitor 1 reset or voltage monitor 2 reset do not affect b2 and b3.
6. The CSPROINI bit in the OFS register is set to 0.

Table 4.2 SFR Information (2)⁽¹⁾

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h			
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU/IIC Interrupt Control Register ⁽²⁾	SSUIC / IICIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 4.6 SFR Information (6)⁽¹⁾

Address	Register	Symbol	After reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIOA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIOA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h			
0161h			
0162h			
0163h			
0164h			
0165h			
0166h			
0167h			
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

5. Electrical Characteristics

The electrical characteristics of N version ($T_{opr} = -20$ to 85°C) and D version ($T_{opr} = -40$ to 85°C) are listed below.

Please contact Renesas Technology sales offices for the electrical characteristics in the Y version ($T_{opr} = -20$ to 105°C).

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage		-0.3 to 6.5	V
V_I	Input voltage		-0.3 to $V_{CC} + 0.3$	V
V_O	Output voltage		-0.3 to $V_{CC} + 0.3$	V
P_d	Power dissipation	$T_{opr} = 25^{\circ}\text{C}$	500 ⁽¹⁾	mW
T_{opr}	Operating ambient temperature		-20 to 85 (N version) / -40 to 85 (D version)	$^{\circ}\text{C}$
T_{stg}	Storage temperature		-65 to 150	$^{\circ}\text{C}$

NOTE:

1. 300 mW for the PTLG0064JA-A package.

Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics⁽⁴⁾

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance ⁽²⁾		10,000 ⁽³⁾	—	—	times
—	Byte program time (program/erase endurance ≤ 1,000 times)		—	50	400	μs
—	Byte program time (program/erase endurance > 1,000 times)		—	65	—	μs
—	Block erase time (program/erase endurance ≤ 1,000 times)		—	0.2	9	s
—	Block erase time (program/erase endurance > 1,000 times)		—	0.3	—	s
t _d (SR-SUS)	Time delay from suspend request until suspend		—	—	97+CPU clock × 6 cycles	μs
—	Interval from erase start/restart until following suspend request		650	—	—	μs
—	Interval from program start/restart until following suspend request		0	—	—	ns
—	Time from suspend until program/erase restart		—	—	3+CPU clock × 4 cycles	μs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		2.2	—	5.5	V
—	Program, erase temperature		-20 ⁽⁸⁾	—	85	°C
—	Data hold time ⁽⁹⁾	Ambient temperature = 55 °C	20	—	—	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. Standard of block A and block B when program and erase endurance exceeds 1,000 times. Byte program time to 1,000 times is the same as that in program ROM.
5. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.
6. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
7. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
8. -40°C for D version.
9. The data hold time includes time that the power supply is off or the clock is not supplied.

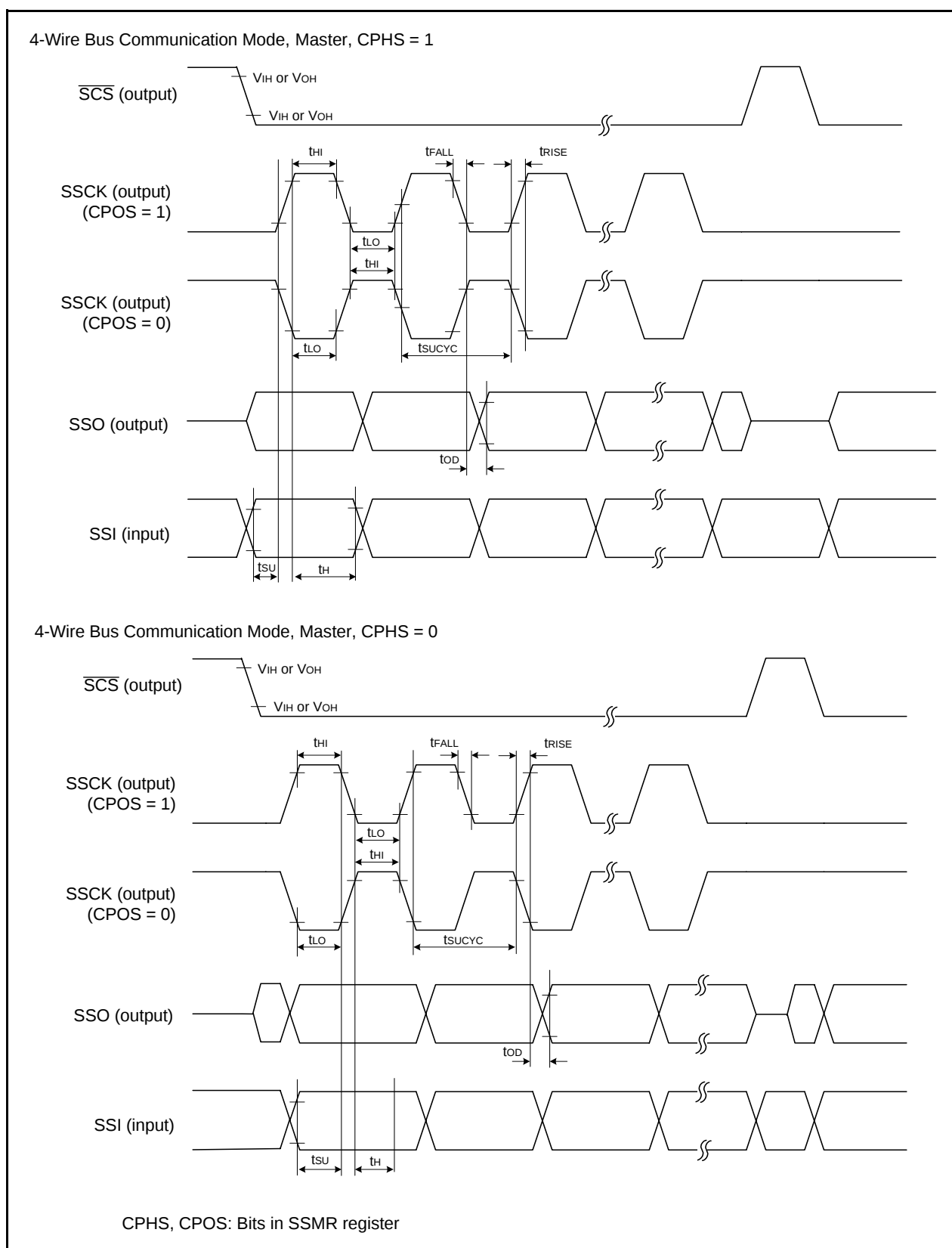


Figure 5.4 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Master)

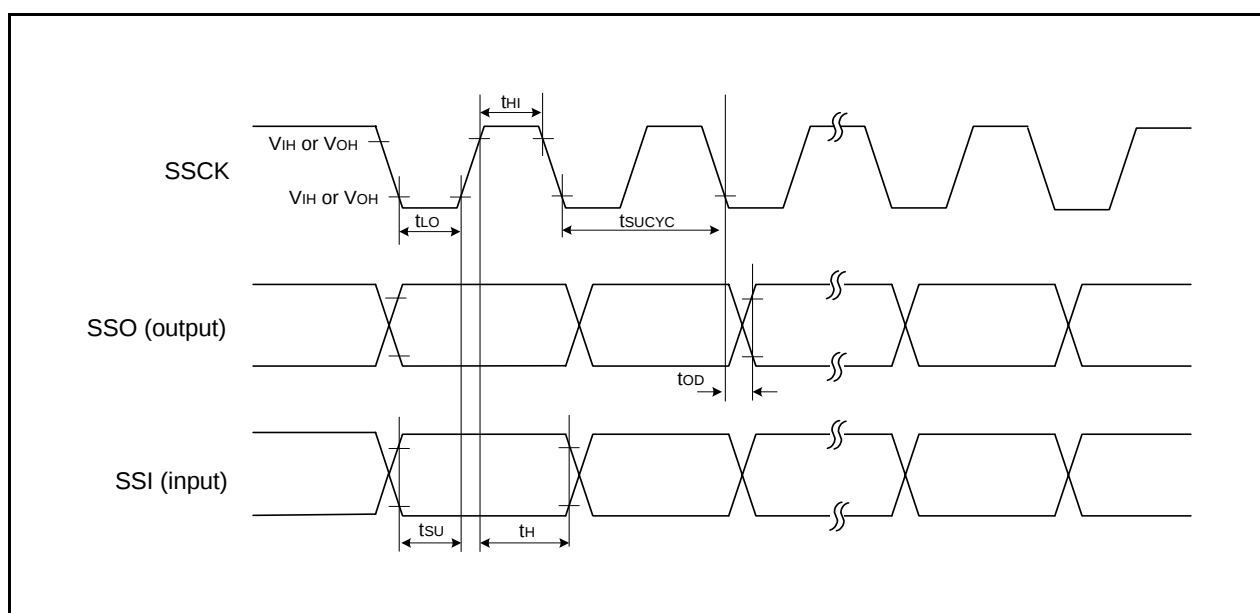


Figure 5.6 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Clock Synchronous Communication Mode)

Table 5.14 Timing Requirements of I²C bus Interface⁽¹⁾

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12t _{CYC} + 600 ⁽²⁾	–	–	ns
t _{SCLH}	SCL input “H” width		3t _{CYC} + 300 ⁽²⁾	–	–	ns
t _{SCLL}	SCL input “L” width		5t _{CYC} + 500 ⁽²⁾	–	–	ns
t _{sf}	SCL, SDA input fall time		–	–	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		–	–	1t _{CYC} ⁽²⁾	ns
t _{BUF}	SDA input bus-free time		5t _{CYC} ⁽²⁾	–	–	ns
t _{STAH}	Start condition input hold time		3t _{CYC} ⁽²⁾	–	–	ns
t _{STAS}	Retransmit start condition input setup time		3t _{CYC} ⁽²⁾	–	–	ns
t _{STOP}	Stop condition input setup time		3t _{CYC} ⁽²⁾	–	–	ns
t _{SDAS}	Data input setup time		1t _{CYC} + 20 ⁽²⁾	–	–	ns
t _{SDAH}	Data input hold time		0	–	–	ns

NOTES:

1. V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V and T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. 1t_{CYC} = 1/f₁(s)

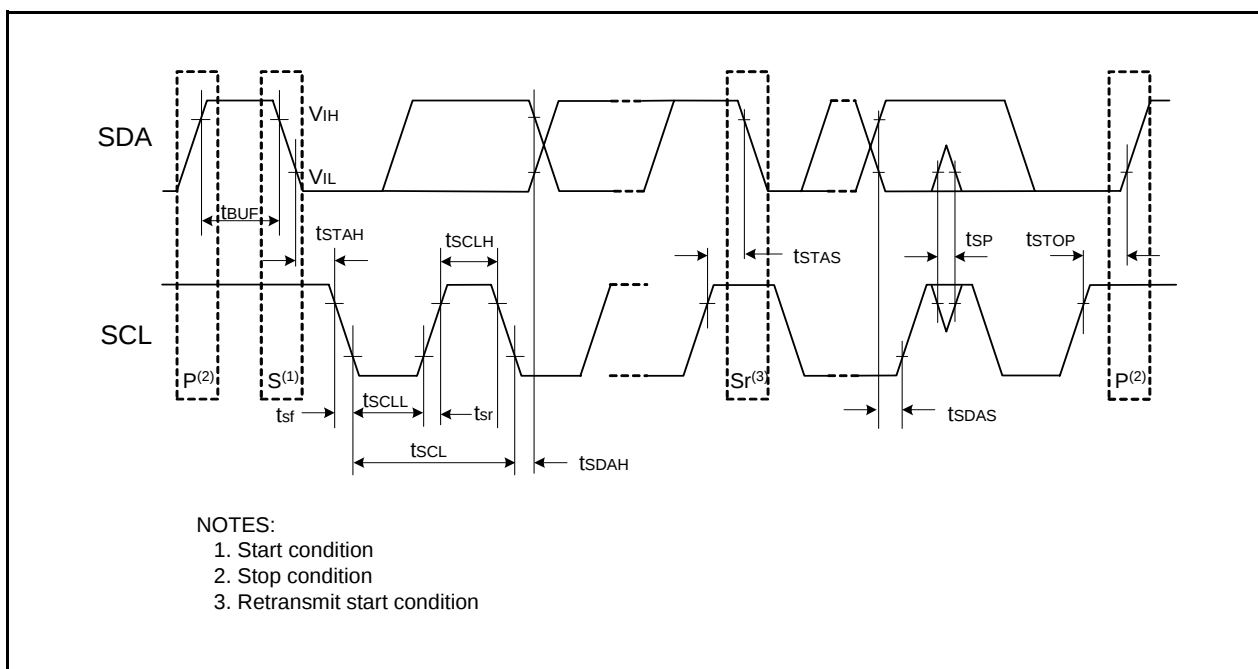
**Figure 5.7 I/O Timing of I²C bus Interface**

Table 5.15 Electrical Characteristics (1) [V_{CC} = 5 V]

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
			I _{OH} = -200 μA	V _{CC} - 0.5	—	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	Drive capacity HIGH I _{OH} = -1 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -500 μA	V _{CC} - 2.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 5 mA	—	—	2.0	V
			I _{OL} = 200 μA	—	—	0.45	V
		P2_0 to P2_7	Drive capacity HIGH I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 5 mA	—	—	2.0	V
		XOUT	Drive capacity HIGH I _{OL} = 1 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 500 μA	—	—	2.0	V
V _{T+} -V _{T-}	Hysteresis	$\overline{\text{INT0}}, \overline{\text{INT1}}, \overline{\text{INT2}}, \overline{\text{INT3}}, \text{KI0}, \text{KI1}, \text{KI2}, \text{KI3}, \text{TRAIO}, \text{RXD0}, \text{RXD1}, \text{CLK0}, \text{CLK1}, \text{SSI}, \text{SCL}, \text{SDA}, \text{SSO}$		0.1	0.5	—	V
		$\overline{\text{RESET}}$		0.1	1.0	—	V
I _{IH}	Input "H" current		V _I = 5 V, V _{CC} = 5V	—	—	5.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 5V	—	—	-5.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 5V	30	50	167	kΩ
R _{FXIN}	Feedback resistance	XIN		—	1.0	—	MΩ
R _{FXCIN}	Feedback resistance	XCIN		—	18	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

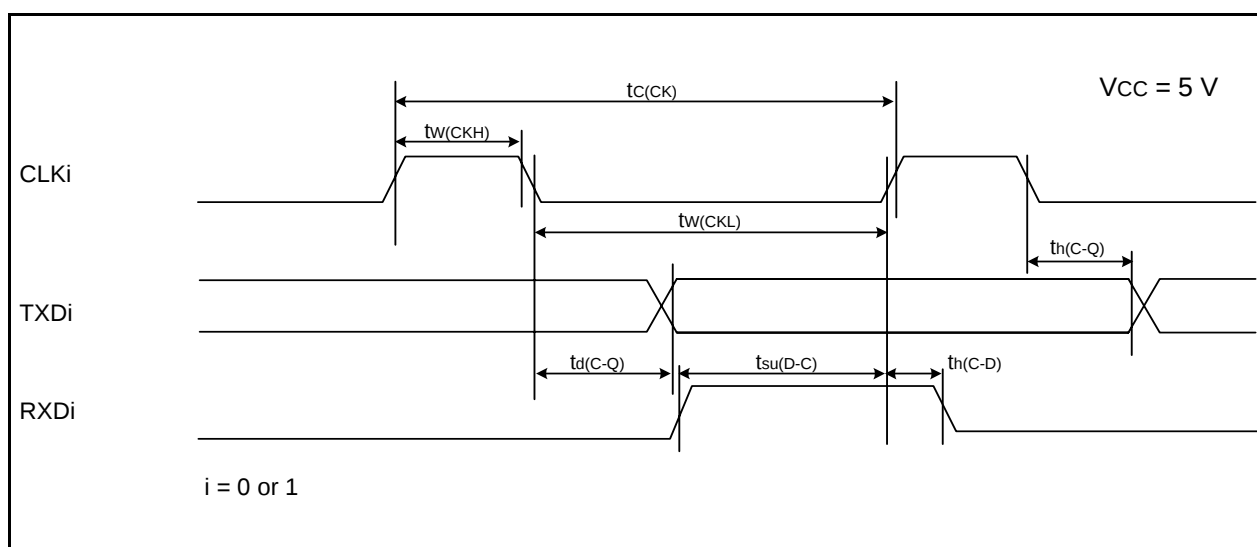
NOTE:

- V_{CC} = 4.2 to 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.20 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200	—	ns
$t_{w(CKH)}$	CLKi input "H" width	100	—	ns
$t_{w(CKL)}$	CLKi input "L" width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	50	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

i = 0 or 1

**Figure 5.10 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.21 External Interrupt $\overline{INTi}$ (i = 0 to 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	250 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	250 ⁽²⁾	—	ns

NOTES:

- When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
- When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

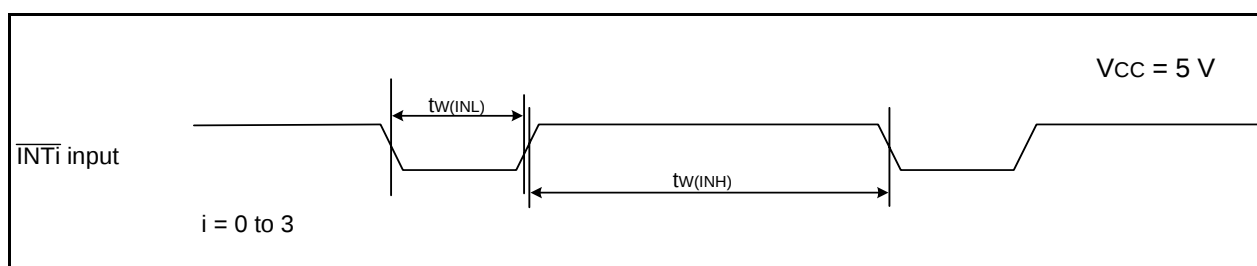
**Figure 5.11 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 5 V**

Table 5.28 Electrical Characteristics (5) [V_{CC} = 2.2 V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -1 mA		V _{CC} - 0.5	—	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH	I _{OH} = -2 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -1 mA	V _{CC} - 0.5	—	V _{CC}	V
		XOUT	Drive capacity HIGH	I _{OH} = -0.1 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -50 μA	V _{CC} - 0.5	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 1 mA		—	—	0.5	V
		P2_0 to P2_7	Drive capacity HIGH	I _{OL} = 2 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 1 mA	—	—	0.5	V
		XOUT	Drive capacity HIGH	I _{OL} = 0.1 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 50 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	$\overline{\text{INT0}}, \overline{\text{INT1}}, \overline{\text{INT2}}, \overline{\text{INT3}}, \text{KI0}, \text{KI1}, \text{KI2}, \text{KI3}, \text{TRAIO}, \text{RXD0}, \text{RXD1}, \text{CLK0}, \text{CLK1}, \text{SSI}, \text{SCL}, \text{SDA}, \text{SSO}$			0.05	0.3	—	V
		$\overline{\text{RESET}}$			0.05	0.15	—	V
I _{IH}	Input "H" current		V _I = 2.2 V		—	—	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V		—	—	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V		100	200	600	kΩ
R _{FXIN}	Feedback resistance	XIN			—	5	—	MΩ
R _{FXCIN}	Feedback resistance	XCIN			—	35	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

NOTE:

- V_{CC} = 2.2 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 5 MHz, unless otherwise specified.

REVISION HISTORY	R8C/24 Group, R8C/25 Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.01	Sep 17, 2004	-	First Edition issued
0.02	Dec 10, 2004	All pages 2, 3 4 5, 6 7 8 9 15 16 19	Part Number revised. R8C/26 → R8C/24, R8C/27 → R8C/25 Table 1.1 R8C/24 Group Performance, Table 1.2 R8C/25 Group Performance - Serial Interface: I²C Bus Interface and Chip-select clock synchronous (SSU) added. - LIN Module added. - Interrupt: Internal factors revised; 10 → 11 - Note on Operating Ambient Temperature added. Figure 1.1 Block Diagram - LIN Module added. - Chip-select clock synchronous (SSU) is added to I²C Bus Interface. Table 1.3 Product Information of R8C/24 Group, Table 1.4 Product Information of R8C/25 Group Date and Development state revised. Figure 1.4 Pin Assignment P3_5/SCL → P3_5/SCL/SSCK, P3_3 → P3_3/SSI, P3_4/SDA → P3_4/SDA/SCS, P3_7 → P3_7/SSO, VSS/AVSS → VSS, XIN/P4_6 → P4_6/XIN, VCC/AVSS → VCC 12pin P1_7/TRAO/INT1 to 22pin P1_0/KIO/AN8 → 20pin P1_7/TRAO/INT1 to 30pin P1_0/KIO/AN8 Table 1.5 Pin Description - Analog Power Supply Input eliminated. - SSU added. Table 1.6 Pin Name Information by Pin Number added. Table 4.1 SFR Information (1) - 0031h: Voltage Detection Register 1 → Voltage Detection <u>A</u> Register 1 - 0032h: Voltage Detection Register 1 → Voltage Detection <u>A</u> Register 2 01000001b → 00100001b (Note 4) - 0036h: "(3), 01000001b (4)" eliminated. - 0038h: Voltage Monitor 0 Control Register (2), VW0C, 00001000b (3), 01000001b (4) added. Table 4.2 SFR Information (2) - 0048h: Timer RD0 Interrupt Control Register, RD0IC, XXXXX000b added. - 0049h: Timer RD Interrupt Control Register, RDIC → Timer RD1 Interrupt Control Register, RD1IC - 004Fh: IIC Interrupt Control Register, IIC → IIC/SSU Interrupt Control Register, IIC2IC Table 4.5 SFR Information (3) - 0106h: LIN Control Register, LINCR, 00h added. - 0107h: LIN Status Register, LINST, 00h added.

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Rev.	Date	Description	
		Page	Summary
0.40	Jan 24, 2006	46	Package Dimensions; “TBD” → “PLQP0052JA-A (52P6A-A)” added
1.00	May 31, 2006	all pages	“Under development” deleted
		1	1. Overview; “data flash ROM” → “data flash” revised
		3	Table 1.2 Functions and Specifications for R8C/25 Group revised
		4	Figure 1.1 Block Diagram; “System clock generator” → “System clock generation circuit” revised
		5 to 6	Table 1.3 Product Information for R8C/24 Group and Table 1.4 Product Information for R8C/25 Group; A part of (D) mark is deleted.
		9	Table 1.6 Pin Name Information by Pin Number NOTE1 added
		15	Table 4.1 SFR Information(1); 001Ch: “00h” → “00h, 10000000b” revised 0029h: High-Speed On-Chip Oscillator Control Register 4 FRA4 When shipping added 002Bh: High-Speed On-Chip Oscillator Control Register 6 FRA6 When shipping added NOTE6 added
		19	Table 4.5 SFR Information(5); 0118h: Timer RE Second Data Register / Counter Data Register, 0119h: Timer RE Minute Data Register / Compare Data Register register name revised
		20	Table 4.6 SFR Information(6); 0143h: “11000000b” → “11100000b” revised
		22	Table 5.2 Recommended Operating Conditions revised
		24	Table 5.4 Flash Memory (Program ROM) Electrical Characteristics revised
		25	Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics revised
		26	Figure 5.2 Time delay until Suspend title revised
		27	Table 5.9 Voltage Monitor 0 Reset Electrical Characteristics → Table 5.9 Power-on Reset Circuit, Voltage Monitor 0 Reset Electrical Characteristics revised Table 5.10 Power-on Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 0 Reset) deleted Figure 5.3 Power-on Reset Circuit Electrical Characteristics revised
		28	Table 5.10 High-speed On-Chip Oscillator Circuit Electrical Characteristics revised Table 5.11 Low-speed On-Chip Oscillator Circuit Electrical Characteristics revised
		35	Table 5.16 Electrical Characteristics (2) [Vcc = 5 V] revised
		39	Table 5.22 Electrical Characteristics (4) [Vcc = 3 V] revised
		43	Table 5.28 Electrical Characteristics (6) [Vcc = 2.2 V] revised
		46	Package Dimensions; “The latest package ... Renesas Technology website.” added

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Rev.	Date	Description	
		Page	Summary
2.00	Jul 14, 2006	all pages	"PTLG0064JA-A (64F0G)" package added
		1	1. Overview; "... or a 64-pin molded-plastic FLGA." added
		2, 3	Table 1.1 Functions and Specifications for R8C/24 Group, Table 1.2 Functions and Specifications for R8C/25 Group; Package: "64-pin molded-plastic FLGA" added
		5	Table 1.3 Product Information for R8C/24 Group, Figure 1.2 Type Number, Memory Size, and Package of R8C/24 Group revised
		6	Table 1.4 Product Information for R8C/25 Group, Figure 1.3 Type Number, Memory Size, and Package of R8C/25 Group revised
		7	Figure 1.4 PLQP0052JA-A Package Pin Assignments (Top View); NOTE3 revised
		8	Figure 1.5 PTLG0064JA-A Package Pin Assignments added
		14	Figure 3.1 Memory Map of R8C/24 Group revised
		15	Figure 3.2 Memory Map of R8C/25 Group revised
		23	Table 5.1 Absolute Maximum Ratings; NOTE1 added
		47	Package Dimensions; "PTLG0064JA-A (64F0G)" added
3.00	Feb 29, 2008	all pages	Y version added Factory programming product added
		2, 3	Table 1.1, Table 1.2 Clock; "Real-time clock (timer RE)" added
		5, 7	Table 1.3, Table 1.4 revised
		6, 8	Figure 1.2, Figure 1.3; ROM number "XXX" added
		16, 17	Figure 3.1, Figure 3.2; "Expanded area" deleted
		18	Table 4.1 revised
		26	Table 5.2 NOTE2 revised
		32	Table 5.10; revised, NOTE4 added Table 5.11; Oscillation stability time: Condition "Vcc = 5.0 V, Topr = 25°C" deleted
		38	Table 5.15; I _{IH} , I _L , R _{PULLUP} Condition: "Vcc = 5V" added
		39	Table 5.16; Condition: High-speed on-chip oscillator mode revised
		40	Table 5.17 added
		41	Figure 5.8 revised
		43	Table 5.22; I _{IH} , I _L , R _{PULLUP} Condition: "Vcc = 3V" added
		44	Table 5.23; Condition "Increase during A/D converter operation" added
		45	Figure 5.12 revised
		48	Table 5.29; Condition "Increase during A/D converter operation" added
		49	Figure 5.16 revised